

FEATURES

- Used in wireless chargers
- High degree of inrush current capability
- Precise melting time
- Surface mount technology allows fuses to be directly attached to printed circuit boards
- Notebook Computer
Wireless Base Station
Networking
Telecom System
- Significant savings in weight and real estate
- RoHS / REACH / AEC-Q200

RS PRO, Fuse, Ceramic SMD LTCC Chip Fuse, Fast Acting, 1A-20A, 1206

RS Stock No.: 2522187
2522188



RS Professionally Approved Products bring to you professional quality parts across all product categories. Our product range has been tested by engineers and provides a comparable quality to the leading brands without paying a premium price.

Surface Mount Fuse — LTCC Chip Fuse

Product Description

Ceramic SMD LTCC Chip Fuse, Fast Acting, 1A-20A, 1206

Applications:

- Storage System Power
- Cooling Fan System
- Battery Management System
- Server Power


General Specifications

Current Rating	1A – 8A	10A, 12A, 15A, 20A
Voltage Rating	63V	24V
Body Material	Ceramic	
Interrupting Ratings	1A – 8A	100A @ 63V DC 50A @ 125V DC
	10A – 20A	150A @ 24V DC
Operating Temperature	-55°C to +125°C	
Country of Origin	Taiwan	

Electrical Characteristics

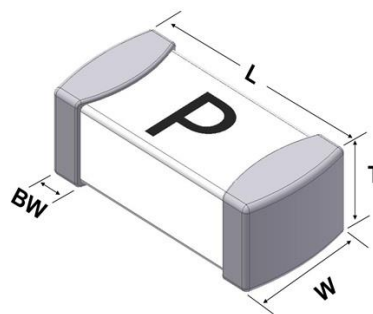
Rated Current	Opening Time	
	1 In Min.	2.5 In Max.
1A-20A	4 hr	5 sec

I²t Nominal Cold Resistance & I²t & Safety Approval:

Approvals	Marking	Interrupting rating		Nominal Cold Resistance (Ohms)	Nominal Melting I ² t (A ² sec.)
1A	H	100A @ 63V DC 50A @ 125V DC	*	0.1750 - 0.3250	0.090
1.5A	K		*	0.0770 - 0.1430	0.113
2A	N		*	0.0455 - 0.0845	0.160
2.5A	O		*	0.0210 - 0.0390	0.188
3A	P		*	0.0182 - 0.0338	0.225
4A	S		*	0.0105 - 0.0195	0.320
5A	T		*	0.0070 - 0.0130	0.750
6A	U		*	0.0063 - 0.0117	0.900
7A	V		*	0.0056 - 0.0104	1.470
8A	W		*	0.0049 - 0.0091	1.728
8A	W	100A @ 63V DC 50A @ 125V DC	*	0.0049 - 0.0091	1.728
10A	10	150A @ 24V DC	*	0.0042 - 0.0078	3.000
12A	12		*	0.0035 - 0.0065	4.320
15A	15		*	0.0028 - 0.0052	6.750
20A	20		*	0.0021 - 0.0039	16.00

Shape & Dimension:

Type	1206
L	3.1 ± 0.2 mm
W	1.6 ± 0.2 mm
T	0.9 ± 0.2 mm
BW	0.5 ± 0.25 mm



Recommended Pad Layout	
L1	1.10 mm
L2	1.52 mm
W	1.78 mm

